

AMENDMENTS TO THE CLAIMS

~~{Claim 1}~~

1. (Currently Amended) A contact pin for contacting a terminal of an electronic device to supply said electronic device with a signal, provided with

a first conductive layer composed of a first conductive material with a high hardness and

a second conductive layer composed of a second conductive material with a lower hardness than said first conductive material.

~~{Claim 2}~~

2. (Currently Amended) A contact pin as set forth in claim 1, wherein said first conductive material has a hardness higher than the oxide film formed on the terminal of said electronic device.

~~{Claim 3}~~

3. (Currently Amended) A contact pin as set forth in claim 1, wherein said second conductive material has a lower hardness than the oxide film formed on the terminal of said electronic device.

~~{Claim 4}~~

4. (Currently Amended) A contact pin as set forth in claim 1, wherein both said first conductive layer and said second conductive layer are exposed at the front end face of the contact pin at the wafer side.

~~{Claim 5}~~

5. (Currently Amended) A contact pin as set forth in claim 1, wherein said first conductive layer is formed at the outside from said second conductive layer.

~~{Claim 6}~~

6. (Currently Amended) A contact pin as set forth in claim 1, wherein said first conductive layer is formed so as to be in close contact with the outside of said second conductive layer.

~~{Claim 7}~~

7. (Currently Amended) A contact pin as set forth in claim 1, wherein said contact pin is formed finely tapered at its front end.

~~{Claim 8}~~

8. (Currently Amended) A contact pin as set forth in claim 1, wherein the pin is further provided with a base material at the outside of which the first conductive layer and second conductive layer are formed, said base material being arranged inside said contact pin with the front end of that base material separated by a predetermined distance from the front end of said contact pin.

~~[Claim 9]~~

9. (Currently Amended) A contact pin as set forth in claim 1, wherein a plurality of at least of said first conductive layer or said second conductive layer is provided.

~~[Claim 10]~~

10. (Currently Amended) A probe card having contact pins of ~~any of claims 1 to 9~~ claim 1 electrically connected to a test head of an electronic device test apparatus and a board upon one main surface of which said contact pins are provided, said contact pins being brought into contact with terminals of an electronic device to test said electronic device.

~~[Claim 11]~~

11. (Currently Amended) ~~An electronic device test apparatus having a test head to which a probe card of claim 10 is electrically connected.~~ A probe card as set forth in claim 10, wherein said first conductive material has a hardness higher than the oxide film formed on the terminal of said electronic device.

12. (New) A probe card as set forth in claim 10, wherein said second conductive material has a lower hardness than the oxide film formed on the terminal of said electronic device.

13. (New) A probe card as set forth in claim 10, wherein both said first conductive layer and said second conductive layer are exposed at the front end face of the contact pin at the wafer side.

14. (New) A probe card as set forth in claim 10, wherein said first conductive layer is formed at the outside from said second conductive layer.

15. (New) A probe card as set forth in claim 10, wherein said first conductive layer is formed so as to be in close contact with the outside of said second conductive layer.

16. (New) A probe card as set forth in claim 10, wherein said contact pin is formed finely tapered at its front end.

17. (New) A probe card as set forth in claim 10, wherein
the pin is further provided with a base material at the outside of which the first conductive layer and second conductive layer are formed,
said base material being arranged inside said contact pin with the front end of that base material separated by a predetermined distance from the front end of said contact pin.

18. (New) A probe card as set forth in claim 10, wherein a plurality of at least of said first conductive layer or said second conductive layer is provided.

19. (New) An electronic device test apparatus having a test head to which a probe card of claim 10 is electrically connected.

20. (New) A electronic device test apparatus as set forth in claim 19, wherein said first conductive material has a hardness higher than the oxide film formed on the terminal of said electronic device.

21. (New) A electronic device test apparatus as set forth in claim 19, wherein said second conductive material has a lower hardness than the oxide film formed on the terminal of said electronic device.

22. (New) A electronic device test apparatus as set forth in claim 19, wherein both said first conductive layer and said second conductive layer are exposed at the front end face of the contact pin at the wafer side.

23. (New) A electronic device test apparatus as set forth in claim 19, wherein said first conductive layer is formed at the outside from said second conductive layer.

24. (New) A electronic device test apparatus as set forth in claim 19, wherein said first conductive layer is formed so as to be in close contact with the outside of said second conductive layer.

25. (New) A electronic device test apparatus as set forth in claim 19, wherein said contact pin is formed finely tapered at its front end.

26. (New) A electronic device test apparatus as set forth in claim 19, wherein the pin is further provided with a base material at the outside of which the first conductive layer and second conductive layer are formed, said base material being arranged inside said contact pin with the front end of that base material separated by a predetermined distance from the front end of said contact pin.

27. (New) A electronic device test apparatus as set forth in claim 19, wherein a plurality of at least of said first conductive layer or said second conductive layer is provided.